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Nakano et al.

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(54) **JOINING METHOD, METHOD FOR PRODUCING ELECTRONIC DEVICE AND ELECTRONIC PART**

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(58) **Field of Classification Search**

None

See application file for complete search history.

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 111 days.

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(30) **Foreign Application Priority Data**

(57) **ABSTRACT**

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In joining a first metal member composed of a first metal to a second metal member composed of a second metal with a joining material interposed therebetween, the joining material including a low melting point metal having a lower melting point than the first metal and/or the second metal, the low melting point metal composing the joining material is Sn or an alloy containing Sn, at least one of the first metal and the second metal is a metal or an alloy which forms an intermetallic compound with the low melting point metal composing the joining material, and heat treatment is performed at a temperature at which the low melting point metal melts in a state of locating the joining material between the first metal member and the second metal member.

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B23K 1/00 (2006.01)

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5 Claims, 2 Drawing Sheets

